

SID

Factory: Rot am See

Article:

572

ML8

Provided:

Landwehr, Melanie

Customer:

Date:

17.12.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	230		2
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		3
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		4
A-RS-FR4-ML-0.61mm-035+035-TG150-HF	50200659	35	L2	5
		610		
		35	L3	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	265		6
		0		7
		0		8
A-RS-FR4-ML-0.61mm-035+035-TG150-HF	50200659	35	L4	9
		610		
		35	L5	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	265		10
		0		11
		0		12
A-RS-FR4-ML-0.61mm-035+035-TG150-HF	50200659	35	L6	13
		610		
		35	L7	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	230		14
		0		15
		0		16
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	17

Thickness after Pressing

B00:

3090 µm

Tol+:

320 µm

Tol-:

320 µm

Dmax:

3410 µm

Dmin:

2770 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

3200 µm

Tol+:

320 µm

Tol-:

320 µm

Dmax:

3520 µm

Dmin:

2880 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

3100 µm

Version 1.2.14.15

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